# **BOURNS®**

- 20 W Pulsed Power Dissipation
- 100 V Capability
- 2 A Continuous Collector Current
- 4 A Peak Collector Current
- Customer-Specified Selections Available

LP PACKAGE (TOP VIEW)



**MDTRAB** 

## absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING			VALUE	UNIT	
	TIPP31		40		
Collector-base voltage (I <sub>E</sub> = 0)	TIPP31A	V	60	V	
	TIPP31B	V <sub>CBO</sub>	80		
	TIPP31C		100		
Collector-emitter voltage (I <sub>B</sub> = 0)	TIPP31		40		
	TIPP31A	.,	60	V	
	TIPP31B	V <sub>CEO</sub>	80		
	TIPP31C		100		
Emitter-base voltage	V <sub>EBO</sub>	5	V		
Continuous collector current			2	Α	
Peak collector current (see Note 1)			4	Α	
Continuous base current			1	Α	
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)	P <sub>tot</sub>	0.8	W		
Pulsed power dissipation (see Note 3)	P <sub>T</sub>	20	W		
Operating junction temperature range	T <sub>j</sub>	-55 to +150	°C		
Storage temperature range	T <sub>stg</sub>	-55 to +150	°C		
Lead temperature 3.2 mm from case for 10 seconds	TL	260	°C		

NOTES: 1. This value applies for  $t_p \le 0.3$  ms, duty cycle  $\le 10\%$ .

- 2. Derate linearly to 150°C case temperature at the rate of 6.4 mW/°C.
- 3.  $V_{CE} = 20 \text{ V}$ ,  $I_{C} = 1 \text{ A}$ ,  $t_{D} = 10 \text{ ms}$ , duty cycle  $\leq 2\%$ .



### electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V <sub>(BR)CEO</sub>	Collector-emitter breakdown voltage	I <sub>C</sub> = 5 mA (see Note 4)	I <sub>B</sub> = 0	TIPP31 TIPP31A TIPP31B TIPP31C	40 60 80 100			V
I <sub>CES</sub>	Collector-emitter cut-off current	$V_{CE} = 40 \text{ V}$ $V_{CE} = 60 \text{ V}$ $V_{CE} = 80 \text{ V}$ $V_{CE} = 100 \text{ V}$	$V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$ $V_{BE} = 0$	TIPP31 TIPP31A TIPP31B TIPP31C			0.2 0.2 0.2 0.2	mA
I <sub>CEO</sub>	Collector cut-off current	V <sub>CE</sub> = 30 V V <sub>CE</sub> = 60 V	I <sub>B</sub> = 0 I <sub>B</sub> = 0	TIPP31/31A TIPP31B/31C			0.3 0.3	mA
I <sub>EBO</sub>	Emitter cut-off current	V <sub>EB</sub> = 5 V	I <sub>C</sub> = 0				1	mA
h <sub>FE</sub>	Forward current transfer ratio	$V_{CE} = 4 V$ $V_{CE} = 4 V$	$I_C = 1 A$ $I_C = 2 A$	(see Notes 4 and 5)	20 10			
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	I <sub>B</sub> = 375 mA	I <sub>C</sub> = 2A	(see Notes 4 and 5)			1	٧
$V_{BE}$	Base-emitter voltage	V <sub>CE</sub> = 4 V	I <sub>C</sub> = 2 A	(see Notes 4 and 5)			1.5	٧
h <sub>fe</sub>	Small signal forward current transfer ratio	V <sub>CE</sub> = 10 V	I <sub>C</sub> = 0.5 A	f = 1 kHz	20			
h <sub>fe</sub>	Small signal forward current transfer ratio	V <sub>CE</sub> = 10 V	I <sub>C</sub> = 0.5 A	f = 1 MHz	3			

NOTES: 4. These parameters must be measured using pulse techniques,  $t_p$  = 300  $\mu$ s, duty cycle  $\leq$  2%.

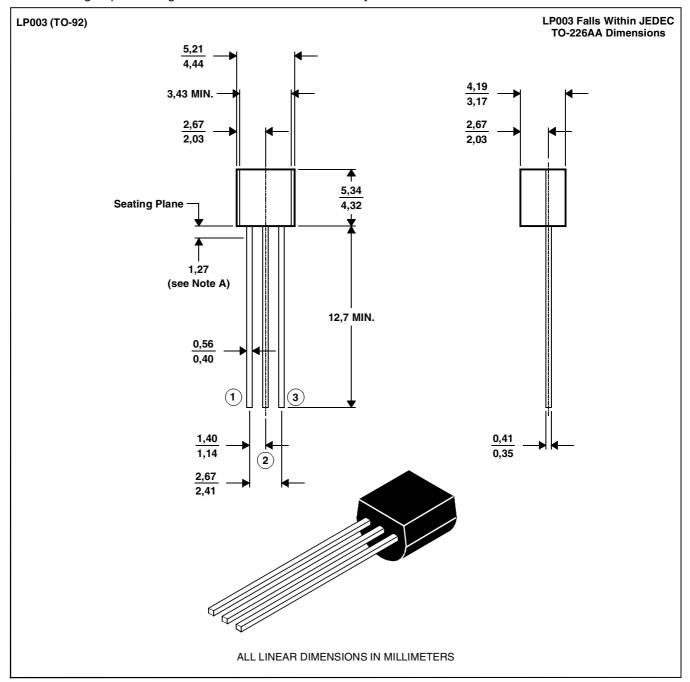
<sup>5.</sup> These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

#### **MECHANICAL DATA**

#### LP003 (TO-92)

#### 3-pin cylindical plastic package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: Lead dimensions are not controlled in this area.

**MDXXAX** 

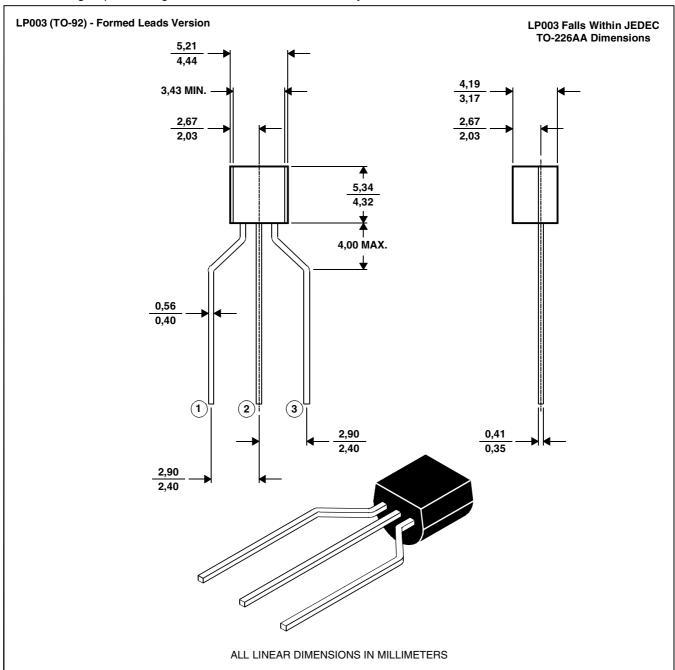


#### **MECHANICAL DATA**

#### LP003 (TO-92)

# 3-pin cylindical plastic package

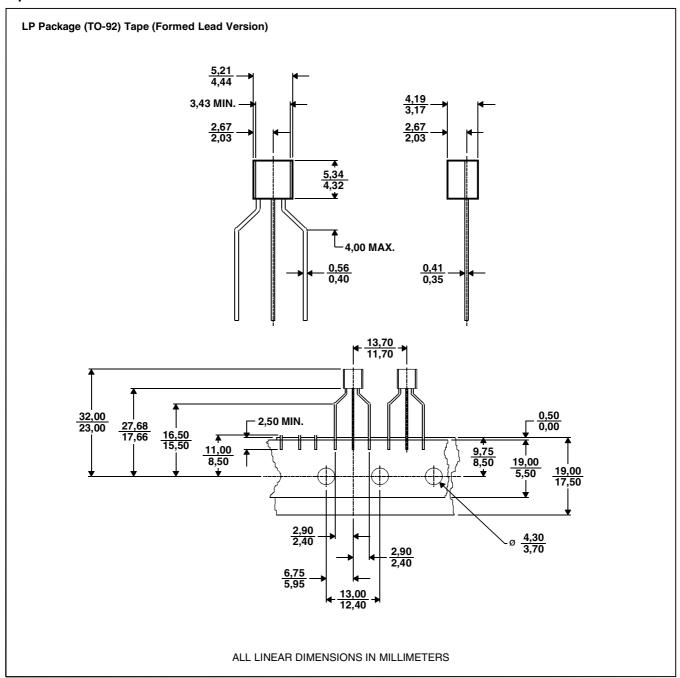
This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



MDXXAR

#### **MECHANICAL DATA**

LPR tape dimensions



MDXXAS